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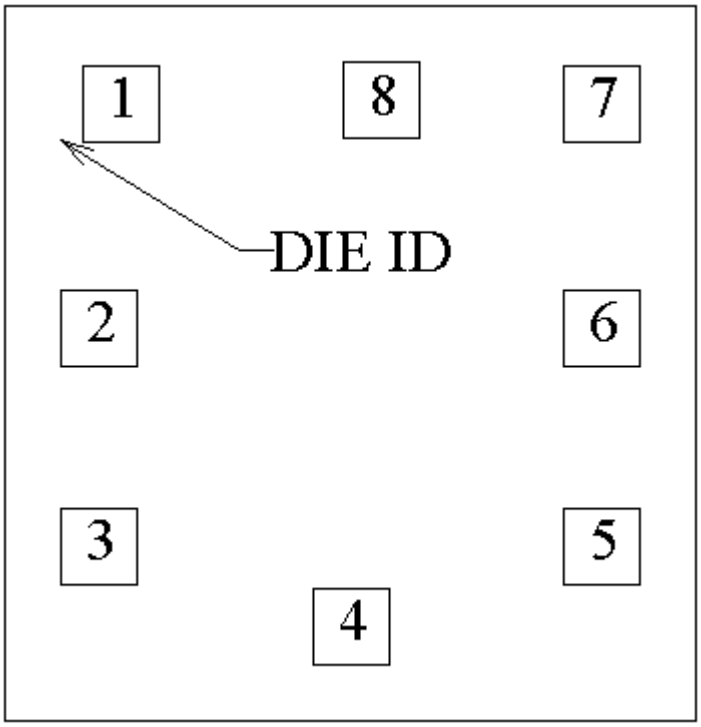
DPBU
Die Datasheet

LM193 MD8 MW8
LOW POWER LOW OFFSET VOLTAGE DUAL COMPARATORS

March 01,2004

DIE LAYOUT (C-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	193C	Bond Pad Opening Size (min)	92µm x 92µm
Die Step	C	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	838µm x 864µm 33.0mils x 34.0mils	Back Side Connection	Floating
Thickness	330µm Nominal		
Min Pitch	259µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (C -Step)

(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
OUTPUT A	1	-277	314	92	x	92
INPUT A-	2	-305	42	92	x	92
INPUT A+	3	-305	-221	92	x	92
GND	4	2	-318	92	x	92
INPUT B+	5	304	-221	92	x	92
INPUT B-	6	304	42	92	x	92
OUTPUT B	7	304	314	92	x	92
V+	8	38	318	92	x	92

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